

Abstract of the Disclosure

Nickel film formation is implemented by heating a deposition chamber during deposition of nickel on a substrate or between processing of two or more substrates or both. Embodiments include forming a nickel silicide on a composite having an exposed silicon surface by introducing the substrate to a PVD chamber having at least one heating element for heating the chamber and depositing a layer of nickel directly on the exposed silicon surface of the composite while concurrently heating the chamber with the heating element.